

Amendments to the Claims:

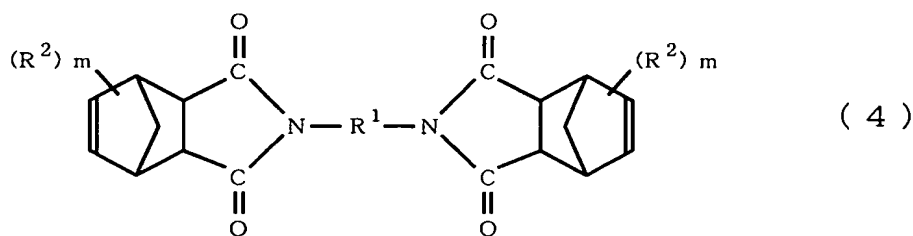
The following listing of claims replaces all prior versions and listings of claims in the application.

Listing of the Claims:

1. (Currently Amended): A resin composition, comprising:
- a resin component containing (A) 40 to 99% by mass of a poly(aryl ketone) and (B) 1 to 60% by mass of a poly(arylene sulfide), and
- (C) 0.1 to 5 parts by mass, per 100 parts by mass of said resin component, of at least one thermosetting imide resin selected from the group consisting of a polyfunctional unsaturated imide compound and a thermoset product thereof, wherein said polyfunctional unsaturated imide compound is a bisnadimide compound represented by the following

Formula (4):

Formula (4)



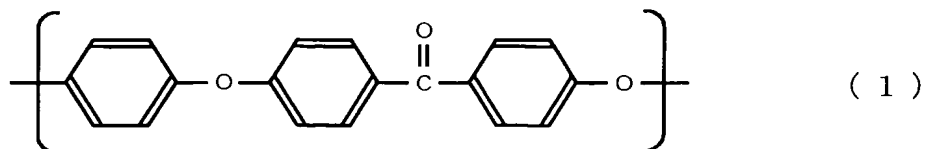
where R¹ is a divalent organic group, R² is a halogen atom, an alkyl group, an alkoxy group, an allyl group, an alkylidene group, an aryl group or an aralkyl group, and m is 0 or an integer of 1 to 6.

2. (Original): The resin composition according to claim 1, wherein said poly(aryl ketone) (A) is at least one poly(aryl ketone) selected from the group consisting of a poly(ether ether ketone) comprising a repeating unit represented by the following formula (1)

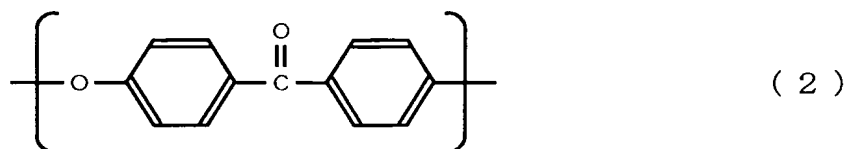
and a poly(ether ketone) comprising a repeating unit represented by the following formula

(2):

Formula (1)



Formula (2)



3. (Original): The resin composition according to claim 1, wherein said poly(arylene sulfide) (B) is a poly(arylene sulfide) having a melt viscosity of 10 to 1,000 Pa·s, as measured at a temperature of 310°C and a shear rate of 1,200/second.

4. (Original): The resin composition according to claim 1, wherein said poly(arylene sulfide) (B) is a poly(phenylene sulfide).

5. (Original): The resin composition according to claim 1, wherein said poly(arylene sulfide) has a pH of up to 8.0, as measured in a mixed water/organic solvent solution regulated to an acetone/water ratio of 1:2.

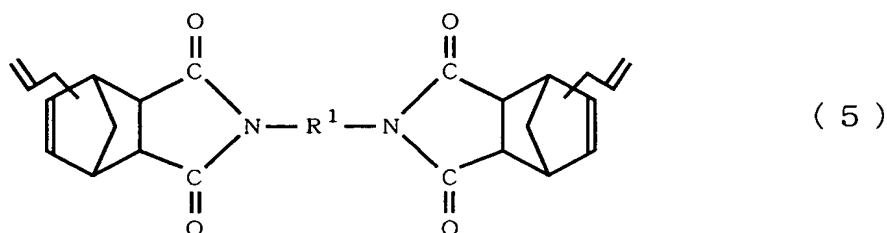
6. (Canceled).

7. (Canceled).

8. (Canceled).

9. (Currently Amended): The resin composition according to claim 8 1, wherein said ~~bisnagiimide~~ bisnadimide compound is a ~~bisallylnagiimide~~ bisallylnadimide compound represented by the following formula (5):

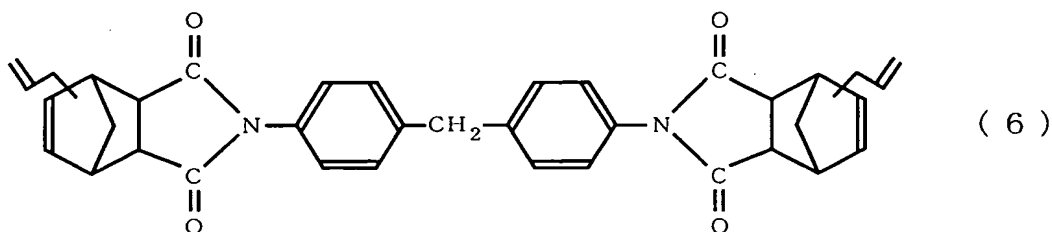
Formula (5)



where R¹ is a divalent organic group.

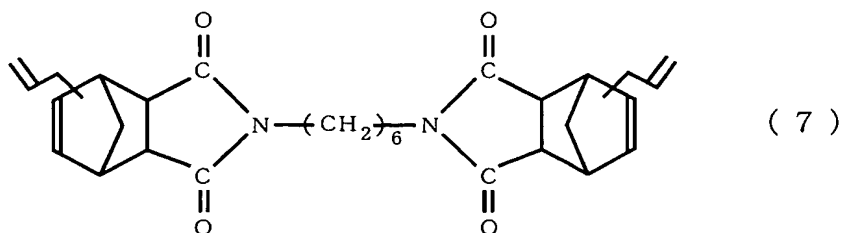
10. (Currently Amended): The resin composition according to claim 9, wherein said ~~bisallylnagiimide~~ bisallylnadimide compound is a compound represented by the following formula (6):

Formula (6)



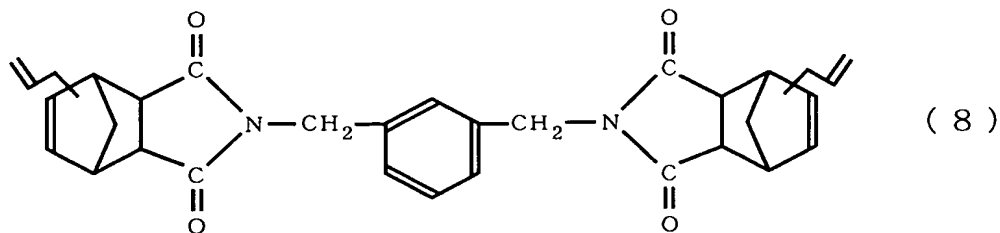
11. (Currently Amended): The resin composition according to claim 9, wherein said ~~bisallylnagiimide~~ bisallylnadimide compound is a compound represented by the following formula (7):

Formula (7)



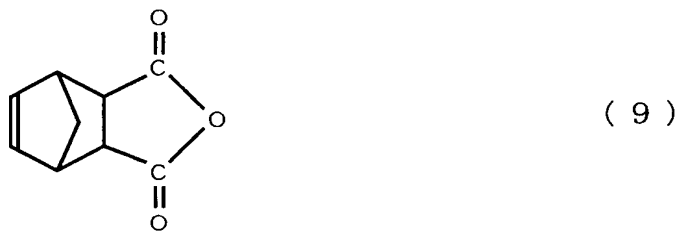
12. (Currently Amended): The resin composition according to claim 9, wherein said ~~bisallylnadimide~~ bisallylnadimide compound is a compound represented by the following formula (8):

Formula (8)



13. (Currently Amended): The resin composition according to claim 9, wherein said ~~bisallylnadimide~~ bisallylnadimide compound has been synthesized by allowing nadic anhydride represented by the following formula (9) or a monoalkyl ester of nadic acid to react with a diamine, followed by a dehydration ring-closure reaction:

Formula (9)



14. (Canceled).

15. (Currently Amended): The resin composition according to claim 1, wherein said thermosetting imide resin (C) is a ~~poly-functional-unsaturated imide~~ bisnadimide compound prior to thermosetting.

16. (Currently Amended): The resin composition according to claim 1, wherein said thermosetting imide resin (C) is a thermoset product of a ~~polyfunctional-unsaturated imide~~ bisnadimide compound.

17. (Currently Amended): The resin composition according to claim 16, wherein said thermoset product is obtained by heating said ~~polyfunctional-unsaturated imide~~ bisnadimide compound at a temperature of 200 to 300°C for 30 minutes to 72 hours for thermosetting.

18. (Currently Amended): The resin composition according to claim 16, wherein said thermoset product is a thermoset product of a ~~bisallylnadimide~~ bisallylnadimide compound.

19. (Original): The resin composition according to claim 1, which further contains a filler in an amount of up to 800 parts by mass per 100 parts by mass of said resin component.

20. (Original): The resin composition according to claim 19, wherein said filler is a fibrous filler.